

	Hits	Search Text	Time Stamp	DBs
9	0	(metallic adj pad and wafer and pick and place).clm.	2005/10/31 10:35	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T

	Hits	Search Text	Time Stamp	DBs
54	77	semiconductor and active same (pad or standoff or stand adj2 off) with tool	2005/10/28 22:25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
55	0	protect\$4 with (semiconductor adj2 (laser or chip)) with ad	2005/10/28 22:27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
56	894	protect\$4 with (semiconductor adj2 (laser or chip)) with pad	2005/10/28 22:27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
57	88	protect\$4 with (semiconductor adj2 (laser or chip)) with pad same wafer	2005/10/28 22:27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
58	12	("4689797"   "4783788"   "4813050"   "4965525"   "5223170"   "5663974"   "5960020"   "5999673"   "6014396"   "6037189"   "6075801"   "6278720").PN.	2005/10/31 08:00	US-PGPUB; USPAT; USOCR

	Hits	Search Text	Time Stamp	DBs
1	6	("4728628"   "4830980"   "5208183"   "5474954"   "5504768"   "5658823") .PN.	2005/10/31 08:06	US- PGPUB; USPAT; USOCR
2	11	("4689797"   "4728628"   "4783788"   "4813050"   "4965525"   "5078516"   "5652812"   "5703895"   "6014396"   "6037189"   "6075801") .PN.	2005/10/31 08:07	US- PGPUB; USPAT; USOCR
3	8	("5228101"   "5353364"   "5412748"   "5621837"   "6021149"   "6058234"   "6108477"   "6343171") .PN.	2005/10/31 08:08	US- PGPUB; USPAT; USOCR
4	1	("5901265") .PN.	2005/10/31 09:49	US- PGPUB; USPAT; USOCR
5	109	pad with kerf and (dicing die singulat\$4 divid\$4 separat\$4)	2005/10/31 09:51	US- PGPUB; USPAT; USOCR
6	6	protect\$4 near3 pad same pick adj2 place	2005/10/31 09:53	US- PGPUB; USPAT; USOCR
7	10	protect\$4 with pad same pick adj2 place	2005/10/31 09:53	US- PGPUB; USPAT; USOCR
8	4	l17 not l16	2005/10/31 09:53	US- PGPUB; USPAT; USOCR